

In re Application of:
Keith Weinstein
Application No.: 10/601,139
Filed: June 10, 2003
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Amendments to the Claims

Please amend claims 1-7 and 9-17 as indicated in the listing of claims.

Please cancel claim 8 without prejudice and disclaimer.

Please add new claim 18 and 19.

The listing of claims will replace all prior versions, and listings of claims in the application.

Listing of Claims:

1. (Currently amended) A ~~gold-based~~ solder composition for assembling, repairing or sizing jewelry comprising of about 25% to 92% by weight gold and at least about 2% to about 14% by weight of an alloy selected from the group consisting of gallium, indium, and copper in a respective weight ratio of approximately 6:3:1 respectively, wherein the solder composition has a melting temperature in a range from about 1000°F to about 1550°F.

2. (Currently amended) A ~~gold-based~~ solder composition according to claim 1, further comprising of ~~at least about 25% to about 92% by weight gold and~~ a mixture of about 8% to ~~about~~ 80% silver, about 1% to ~~about~~ 66% copper, about 5% to ~~about~~ 31% zinc and about 0% to ~~about~~ 35% nickel.

3. (Currently amended) A ~~gold-based~~ solder composition according to claim 1, wherein the composition is consisting essentially of about 25% by weight gold.

4. (Currently amended) A ~~gold-based~~ solder composition according to claim 1, wherein the composition is consisting essentially of about 41.6% by weight gold.

5. (Currently amended) A ~~gold-based~~ solder composition according to claim 1, wherein the composition is consisting essentially of about of about 58.3% by weight gold.

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6. (Currently amended) A ~~gold-based~~ solder composition according to claim 1, wherein the composition is consisting essentially of about 75% by weight gold.

7. (Currently amended) A ~~gold-based~~ solder composition according to claim 1, wherein the composition is consisting essentially of about 91.6% by weight gold.

8. (Canceled).

9. (Currently amended) A ~~gold-based~~ solder composition according to claim 1, wherein the solder composition has a melting temperature in the range from about 1100°F to ~~about~~ 1550°F.

10. (Currently amended) An alloy for lowering the melting point of a gold solder ~~when combined therewith to provide a solder having a reduced melting point, the alloy~~ comprising ~~of at least~~ about 2% to ~~about~~ 14% by weight gallium, indium and ~~cooper~~ copper in a respective weight ratio of approximately 6:3:1 ~~respectively, wherein the said solder composition~~ has a reduced melting temperature as compared to a solder not having the alloy in the range from about 1000°F to about 1550°F.

11. (Currently amended) A ~~The gold-based solder composition~~ according to claim ~~10~~ 18, further comprising ~~of at least about 25% to about 92% by weight gold and a mixture of about 8% to about 80% silver, about 1% to about 66% copper, about 5% to about 31% zinc and about 0% to about 35% nickel.~~

12. (Currently amended) A ~~The gold-based solder composition~~ according to claim ~~11~~ 18, wherein the solder is consisting essentially of about 25% by weight gold.

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13. (Currently amended) A ~~The gold-based solder composition~~ according to claim ~~11~~
18, wherein the solder is consisting essentially of about 41.6% by weight gold.

14. (Currently amended) A ~~The gold-based solder composition~~ according to claim ~~11~~
18, wherein the solder is consisting essentially of about 58.3% by weight gold.

15. (Currently amended) A ~~The gold-based solder composition~~ according to claim ~~11~~
18, wherein the solder is consisting essentially of about 75% by weight gold.

16. (Currently amended) A ~~The gold-based solder composition~~ according to claim ~~11~~
18, wherein the solder is consisting essentially of about 91.6% by weight gold.

17. (Currently amended) A ~~The gold-based solder composition~~ according to claim ~~11~~
18, wherein the solder composition has a melting temperature in the range from about 1100
1000°F to about 1550°F.

18. (New) A gold solder composition comprising of about 25% to 92% by weight gold
and an alloy for lowering the melting point of the solder comprising about 2% to 14% by weight
gallium, indium and copper in a respective weight ratio of approximately 6:3:1.

19. (New) The gold solder according to claim 18, wherein the solder has a melting
temperature in the range from about 1100°F to 1550°F.